

Title (en)

Method for assembling micro injecting device and apparatus for the same

Title (de)

Verfahren zum Zusammenbau einer Mikrospritzvorrichtung und dazugehöriger Apparat

Title (fr)

Procédé d'assemblage d'un micro-dispositif d'injection et appareil pour sa mise en oeuvre

Publication

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Application

EP 99308741 A 19991103

Priority

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Abstract (en)

A method for assembling a micro-injecting device and an apparatus for assembling the device are disclosed. A heater chip wafer on which a plurality of heater chips are formed is fixed onto a vacuum bench, and a membrane manufactured independently of a jet chip is aligned to be separated by a predetermined space from the heater chip wafer, and the membrane is fixed on the heater chip wafer. This avoids the membrane being moved frequently in the process of aligning and assembling, thus obtaining in-advance prevention against damage to the membrane, and elimination of the necessity to align the membrane to each heater chip, thereby reducing significantly the time required for assembling. <IMAGE>

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Citation (applicant)

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